



DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING APPARATUS

the specification of which is attached hereto unless the following is checked

was filed on _____ as United States Application Number or PCT International

Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

(List prior foreign applications. See note A)

(Number)	Japan (Country)	20/9/2002 (Day/Month/Year Filed)	Priority Claimed
2002-276076	Japan (Country)	20/9/2002 (Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
_____	(Country)	(Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____	(Country)	(Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____	(Country)	(Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No

(See note B)

See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List prior U.S. Applications)

(Application Serial No.)	(Filing Date)
_____	(Filing Date)
_____	(Filing Date)

Status

- | | | |
|-----------------------------------|----------------------------------|------------------------------------|
| <input type="checkbox"/> Patented | <input type="checkbox"/> Pending | <input type="checkbox"/> Abandoned |
| <input type="checkbox"/> Patented | <input type="checkbox"/> Pending | <input type="checkbox"/> Abandoned |
| <input type="checkbox"/> Patented | <input type="checkbox"/> Pending | <input type="checkbox"/> Abandoned |

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

23850
PATENT TRADEMARK OFFICE

Please direct all communications to the following address:

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PATENT TRADEMARK OFFICE

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C) Full name of sole or first inventor (given name, family name) **Sadayoshi HORII**
Inventor's signature *Sadayoshi Horie* Date March 28, 2005
Residence Same as the Post Office Address Citizenship Japanese
Post Office Address c/o HITACHI KOKUSAI ELECTRIC INC.
14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

Full name of second inventor (given name, family name) **Hironobu MIYA**
Inventor's signature *Hironobu Miya* Date March 28, 2005
Residence Same as the Post Office Address Citizenship Japanese
Post Office Address c/o HITACHI KOKUSAI ELECTRIC INC.
14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

Full name of third inventor (given name, family name) **Yoshiaki HASHIBA**
Inventor's signature *Yoshiaki Hashiba* Date March 28, 2005
Residence Same as the Post Office Address Citizenship Japanese
Post Office Address c/o HITACHI KOKUSAI ELECTRIC INC.
14-20, Higashi-Nakano 3-chome, Nakano-ku, Tokyo 164-8511 Japan

Full name of fourth inventor (given name, family name)
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

Full name of fifth inventor (given name, family name)
Inventor's signature _____ Date _____
Residence _____ Citizenship _____
Post Office Address _____

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(List prior foreign applications. See note A)	Priority Claimed
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_____ (Number)	_____ (Country) _____ (Day/Month/Year Filed)
_____ (Number)	_____ (Country) _____ (Day/Month/Year Filed)
_____ (Number)	_____ (Country) _____ (Day/Month/Year Filed)
(See note B)	<input type="checkbox"/> See attached list for additional prior foreign applications

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(List prior U.S. Applications)	Status
_____ (Application Serial No.)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned
_____ (Application Serial No.)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned
_____ (Application Serial No.)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned

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(See note C)	Full name of sole or first inventor (given name, family name)	Susumu HORITA
	Inventor's signature	Date April 5, 2005
	Residence	Citizenship Japanese
	Post Office Address	1-50, Asahidai, Nomi-shi, Ishikawa 923-1211 Japan
<hr/>		
	Full name of second inventor (given name, family name)	Yasunori NAKATA
	Inventor's signature	Date April 5, 2005
	Residence	Citizenship Japanese
	Post Office Address	268-4, Kubo 6-chome, Kanazawa-shi, Ishikawa 921-8151 Japan
<hr/>		
	Full name of third inventor (given name, family name)	Masao SEKI
	Inventor's signature	Date April 5, 2005
	Residence	Citizenship Japanese
	Post Office Address	35, Nakamachi, Mattou-shi, Ishikawa 924-0877 Japan
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	Full name of fourth inventor (given name, family name)	
	Inventor's signature	Date
	Residence	Citizenship
	Post Office Address	
<hr/>		
	Full name of fifth inventor (given name, family name)	
	Inventor's signature	Date
	Residence	Citizenship
	Post Office Address	
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